

Approval Sheet

Products	Dielectric Chip Antenna		
Customer	Movon		
Model		MF360	
Customer CODE			
Supplier		PARTRON	
Supplier CODE		ACS2450GBAMF36	
	By designed	By checked	By approved
Movon			
	By designed	By checked	By approved
PARTRON	with	*	例从
	Research 5 Team	Quality Assurance	Laboratory
	Chanik.Jeon	Kwang-Gyu.Lee	Byoung-Jun.Yim
	06/11	06/11	06/11

2007. 06. 11



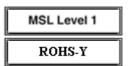
33 Banwol-dong, Hwaseong-si, Gyeonggi-do, Korea 455-300

Tel: 82-31-201-7870~6 Fax: 82-31-201-7800 www.partron.co.kr

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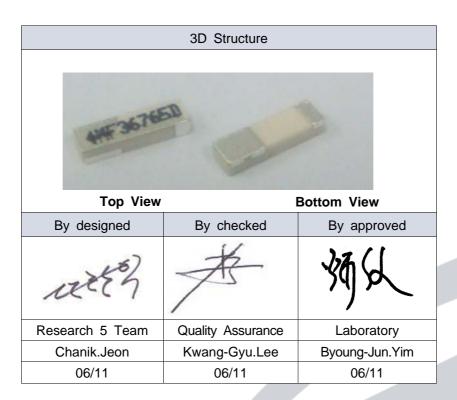






SPECIFICATION

MODEL: ACS2450GBAMF36



2007. 06. 11



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1. Revision

Revision No	Originator	Description of changes	Date of changes
Ver 1.0	Chanik.Jeon	Issued	2007.06.11



2. Summary of Parts

 This product is the internal dielectric chip antenna of radio communication, forms the pattern with Ag paste on the brick of dielectric block and materializes the characteristics

Туре	Only Bulk Ceramic		
Matarial	Dielectric Block	Mg ₂ SiO ₄ (Magnesium Silicate)	
Material	Electrode Paste	Ag	
	$W = 2.0\pm0.1$		
Size[mm]	$L = 7.0\pm0.1$	Ag Paste	
	$T = 1.2\pm0.1$	W	
Flatness Level	0.04		
MSL Level	MSL Level 1	L Dietetric Block	
ESD Level	More than 15 KV (HBM CLASS 3B)	Top - Side View Bottom - Side View	
Version	Revision 1.0		

3. Critical to Quality (

- The following list is specified as the emphasis management list and managed.

CTQ ITEM	Specification Reason	
Shape weight, size	Shape weight and size determines the electric block size after plastic and the dielectric block size effects the level of detail for the printing.	
Plastic Size	The size after plastic effects the level of detail for the printing.	
Printing Size	The level of detail for printing size is an essential list of the BT antenna.	

CTF ITEM 🐟	Specification Reason
Single Element measurement SWR	An important Parameter classifying the electrical characteristics.

- require attention for the following list.

ITEM	Content
Keeping	Sealing tightly when keeping for a long time.
Action	Maybe characteristics changes when changing any design.

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4. Electrical Characteristics

4.1 Single Element SPEC

ITEM	SPEC
Frequency Range [MHz]	2400 ~ 2485
SWR [Max]	3 : 1 (Typ 2 : 1)
Input Impedance $[\Omega]$	50
Polarization	Linear
Gain (Peak / Avg) [dBi]	2.5 / 0
Temperature [℃]	-40 ~ +80
Humidity [%]	At the normal temperature, RH 100

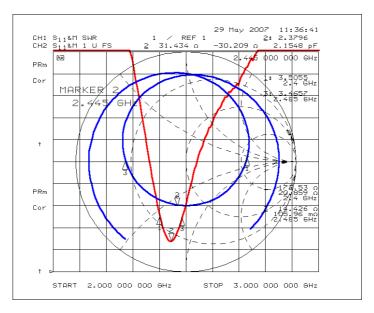
4.2 Set Condition

ITEM			SPEC		
Frequency Range [MHz]			2400 ~ 2485		
	SWR	[Max]		3 : 1	
	Input Impe	dance [Ω]		50 Ohm	
	Polariz	zation		Linear	
	Total Gair	n (Peak / /	Avg) [dBi]	0.5/-3.5	
		Thoto	Peak	-1.82	
	Λ = i.e.o	Theta	Average	-3.62	
	Azimuth	Phi	Peak	-12.72	
			Average	-18.62	
		That	Thoto	Peak	-5.32
Gain[dBi]		Theta	Average	-12.55	
	Elevation 1		Peak	1.05	
		Phi	Average	-3.63	
	Elevation 2	Th4-	Peak	-7.99	
		meta	Theta Average	-13.05	
	Lievation 2	Dhi	Peak	1.21	
	Phi	Average	-3.48		

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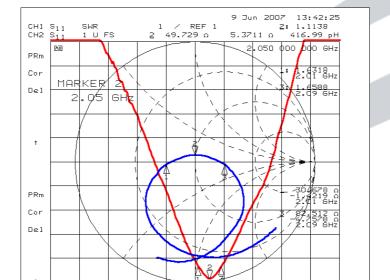
4.3 S11 Graph of Set Condition



4.4 Test Fixture Condition

ITEM	SPEC
Frequency Range [MHz]	2010 ~ 2090
Lower frequency(2010MHz) SWR [Min~Max]	1.2 ~ 2.4 : 1 (Typ 2.0 : 1)
Upper frequency(2090MHz) SWR [Min~Max]	1.2 ~ 2.4 : 1 (Typ 2.0 : 1)

4.5 S11 Graph of Test Fixture Condition



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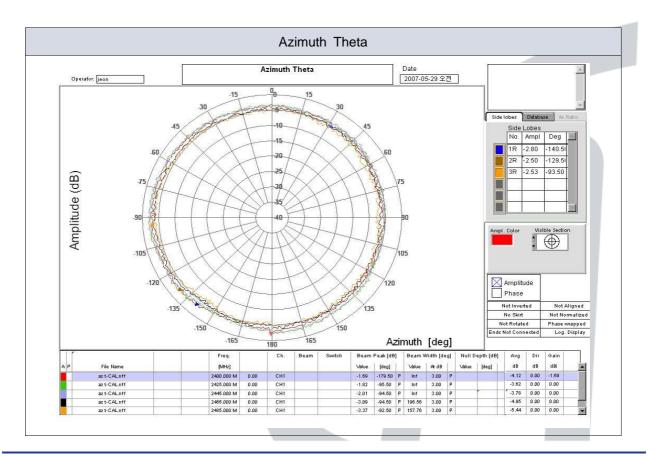
STOP 2.500 000 000 6Hz

START 1.500 000 000 6Hz



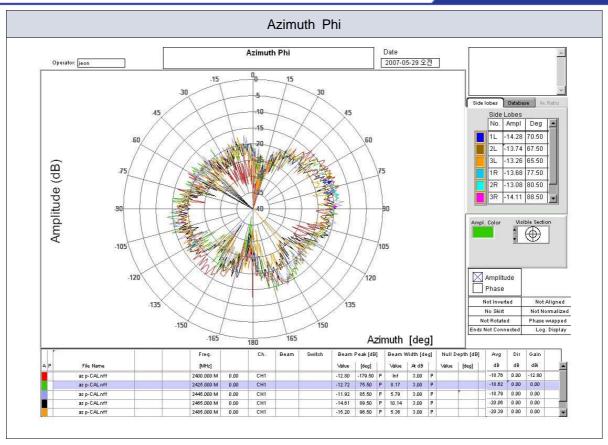
4.6 Radiation Pattern

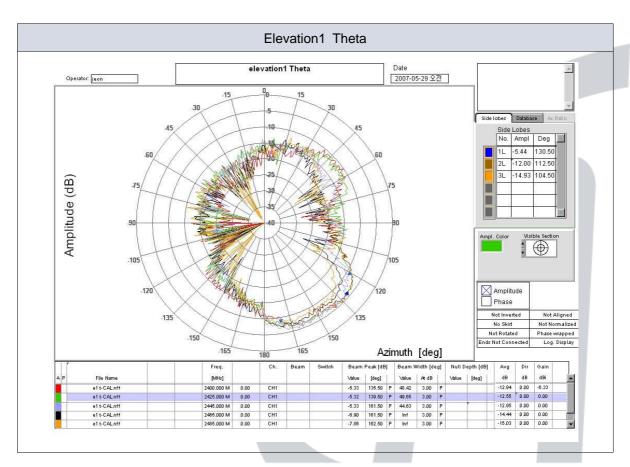
Azimuth Plane	Elevation1 Plane	Elevation2 Plane
270° 90°	90° 180°	270° — 90° — 90° — 180°
Theta	Vertical field of	measured plane
Phi	Horizontal field of measured plane	



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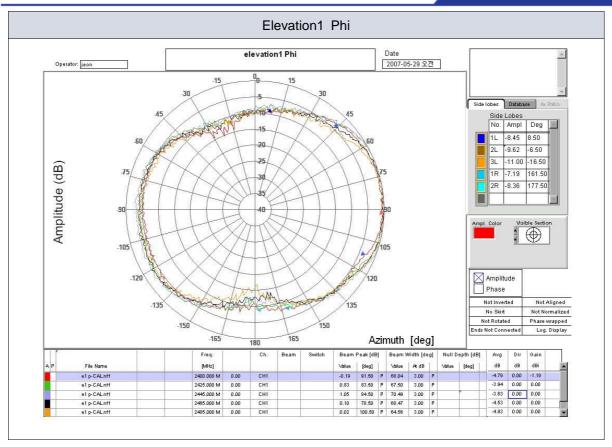


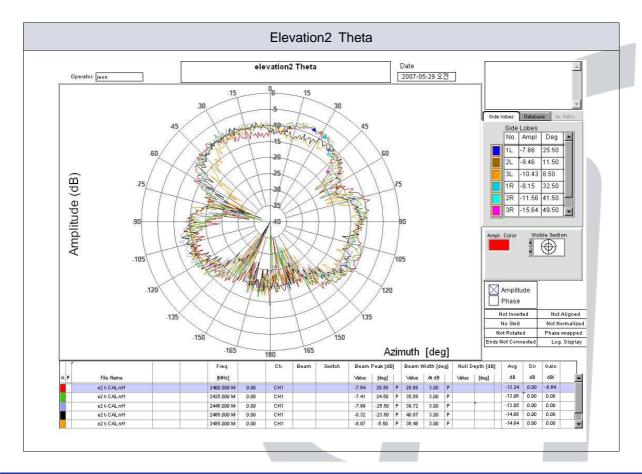




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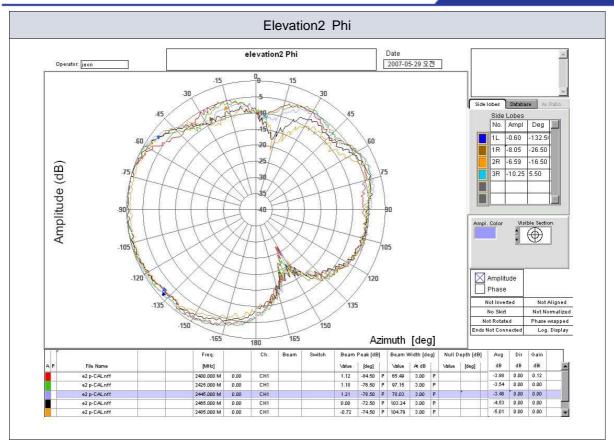






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5. Measurement Process

5.1 SWR/Return loss

Use Network Analyzer when measuring SWR/Return loss and selecting standard SPL. Use automatic inspection equipment when selecting superior and inferior goods.

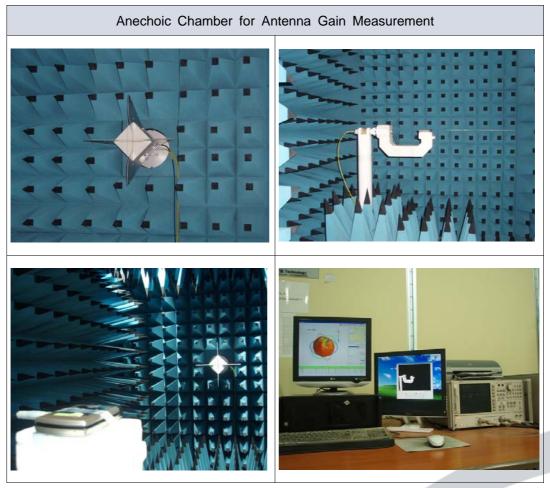
	Set Condition	Test Fixture Condition
Network Analyzer	Agilent HP8753D	Agilent HP8753D or Advantest R3765CH
Cable	RF cable(300mm)	RF cable(300mm)
Test		

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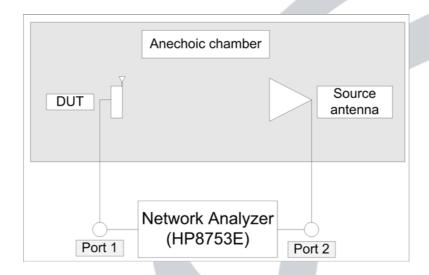


5.2 Gain

Antenna gain is measured in the Anechoic Chamber of this company, using set above of 4.1 list.



5.3 Gain test block diagram

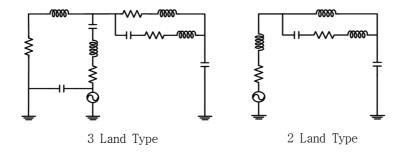


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6. Internal Block Diagram

This product is made of the dielectric block and RF part materialized the characteristics by structural change of Ag pattern on the brick of dielectric block and conditioning value of the structural equivalent circuit.



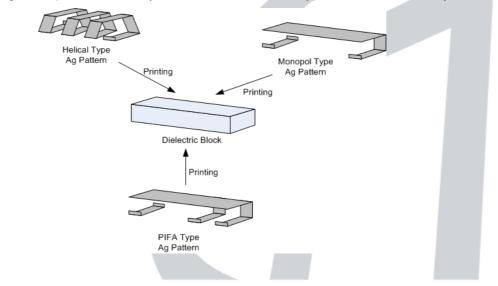
7. Basis Action / Application Note

This product is the internal dielectric chip antenna of radio communication, coverts the electric signal advanced along by transmission line into free space wave.

This product will be mounted wherever you want and the design is revised by mount condition. But require attention to select the mount position, because this product is the radiation part and changed characteristics by boundary condition,



As the following, this product is easy to revise the various types for the boundary condition.

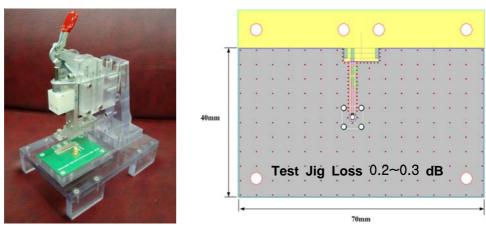


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8. Measurement Jig SPEC

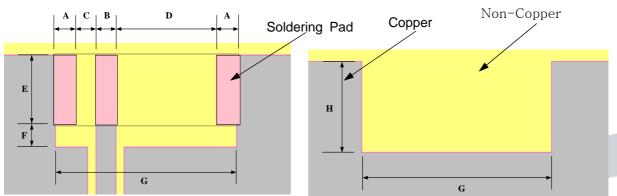
8.1 Test Fixture And GROUND Condition



※ Ev B'd and Test Fixture Jig is the same

(Contact way of Ev B'd is soldering, Test Fixture is copper contact way)

8.2 PCB Layout & Soldering Pad Dimension



Top Layout

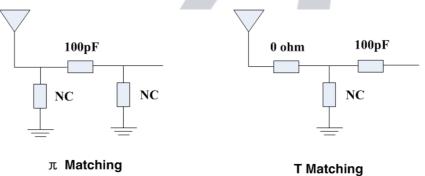
Bottom Pattern

Parameter	А	В	С	D	Е	F	G	Н
Value[mm]	1.1	1.0	0.5	3.5	2.2	1.0	7.2	3.2

Unit; mm

Unless specified tolerances are ±0.1

8.3 Matching Circuit And Reference Value

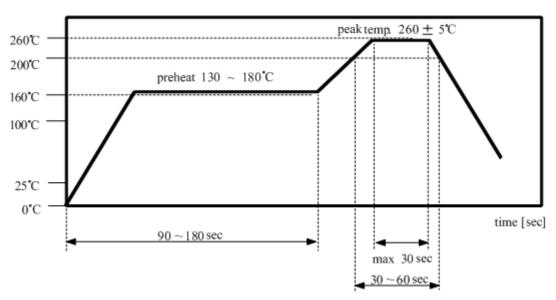


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9. REFLOW PROFILE

9.1 Reflow Soldering

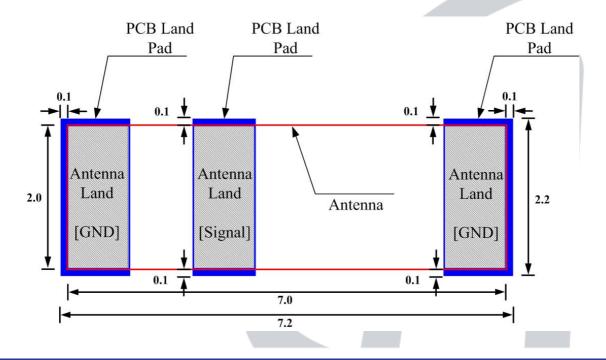


9.2 Manual Soldering

Soldering Temperature : 340 $^{\circ}\text{C} \pm 5\,^{\circ}\text{C}$, 5sec max per each terminal

9.3 PCB Pattern Design

As the following, the PCB land pattern lays out 0.1mm outside land pattern of antenna more than indicated antenna land dimension



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10. Primary Inspection List

Item	Electrical Characteristic [MHz]			Ev B'd Characteristic [MHz]		Size [mm]		
0, 1, 1	VSWR 3.0 Max		VSWR 3	VSWR 3.0 Max		. 7.0.1.0.1	T 1 0 1 0 1	
Standard	2010	2090	2010	2090	$W=2.0\pm0.1$	L=7.0±0.1	T=1.2±0.1	
1	2.00	2.06	1.95	2.22	2.02	7.01	1.23	
2	1.99	2.12	2.24	1.96	2.03	7.02	1.23	
3	1.97	2.06	1.95	2.13	2.03	7.03	1.23	
4	1.87	2.18	2.14	2.10	2.03	7.01	1.22	
5	1.93	2.11	2.25	2.02	2.02	7.01	1.23	
6	2.00	2.01	2.08	2.42	2.04	7.01	1.24	
7	2.09	2.00	2.23	2.22	2.02	7.02	1.24	
8	1.91	2.18	1.87	2.29	2.03	7.02	1.22	
9	2.03	2.18	1.99	2.28	2.02	7.02	1.24	
10	1.98	2.07	2.22	1.86	2.03	7.02	1.24	
11	1.89	2.10	1.86	1.78	2.03	7.03	1.23	
12	1.82	2.17	1.85	1.95	2.02	7.03	1.24	
13	1.97	2.05	2.03	2.37	2.04	7.02	1.22	
14	1.90	2.12	1.86	2.27	2.02	7.01	1.23	
15	1.82	2.04	2.07	1.78	2.03	7.01	1.23	
16	2.07	2.00	1.81	1.80	2.03	7.02	1.24	
17	2.06	2.07	1.86	1.82	2.02	7.03	1.22	
18	2.06	2.05	2.04	1.76	2.04	7.03	1.24	
19	1.97	2.12	1.82	1.77	2.02	7.01	1.23	
20	1.89	2.11	1.91	1.99	2.02	7.02	1.24	
Min	1.82	2	1.81	1.76	2.02	7.01	1.22	
Max	2.09	2.18	2.25	2.42	2.04	7.03	2.24	
X	1.96	2.09	2.00	2.03	2.02	7.01	1.23	
σ	0.08	0.05	0.09	0.09	0.01	0.01	0.01	
Cpk	4.25	2.11	2.17	2.10	3.28	3.38	2.91	
Decision	OK	OK	OK	OK	OK	OK	OK	

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11. Reliability Condition

11.1 Environment Test

ITEM	TEST CONDITION	LIMIT
High Temperature Action	85℃±3℃, 1hr	
High Temperature Resistance	+85°C±3°C, 120hr±2hr	
Low Temperature Action	-40℃±3℃, 1hr	After test, Must meet the
Low Temperature Resistance	-40°C±3°C, 120hr±2hr	characteristics spec of 4.5 list
Humidity Action	+85±3℃, RH85%	
Humidity Resistance	+85±3℃, RH85%, 120hr±2hr	

11.2 Thermal shock test, Reflow test

ITEM	TEST CONDITION	LIMIT
	condition : $-40^{\circ}\text{C} \pm 3^{\circ}\text{C}/1\text{min} \leftrightarrow +85^{\circ}\text{C} \pm 3^{\circ}\text{C}/1\text{min}$	
Thermal shock	Test Cycle : 32 cycle	After test, Must meet the
	Temperature change time : within 5 min	characteristics spec of
Doflow	Pre Heating : 200±5℃, 30∼60 sec	4.5 list
Reflow	Peak Heating : 260℃±5℃, 30sec Max	

11.3 Mechanical Test

ITEM	TEST CONDITION	LIMIT
Vibration	Freq: 10~500Hz , Acceleration: 10 ×9.8m/s (G)	
VIDIALION	Sweep time: 15 min , X.Y.Z each 5 times	After test, Must meet the
	18 times free fall Using the drop jig 152cm high	characteristics spec of
Drop	Jig: 120g±20g Plastic Jig	4.5 list
	Bottom : Concrete or Iron	

11.4 MSL LEVEL Test

1) JEDEC J-STD-020C Test

	F	loor Life	Soak F	Requirements
	Time Conditions		Time	Conditions
1	Unlimited	= < 30°C/85%RH	168+5/-0	= < 85°C/85%RH

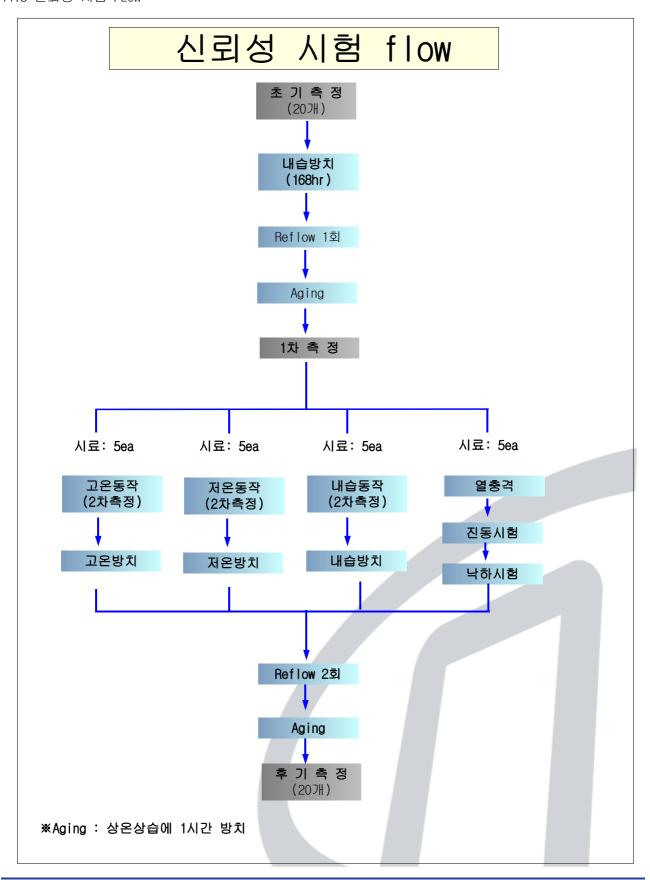
2) Test Condition

ITEM	Conditon	LIMIT
Soak Requirements	After leaving +85±3℃, RH85% 168hr±2hr 2 times Reflow without aging	After test, Must meet the characteristics spec of 4.5 list

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11.5 신뢰성 시험 FLOW

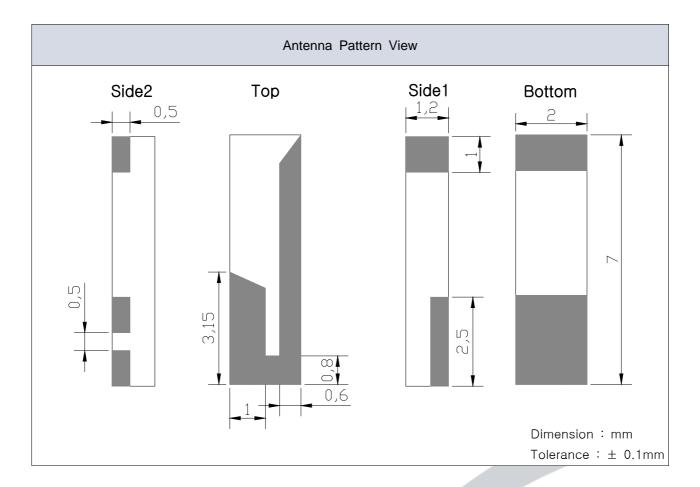


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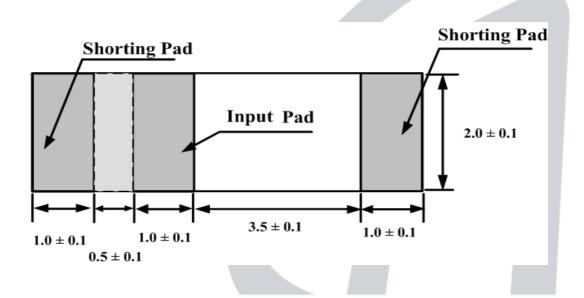


12. Mechanical Characteristics

12.1 Antenna Pattern Dimension



12.2 Pin name



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12.3 Lot number notation

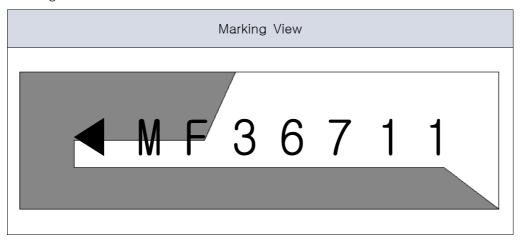
7 <u>1</u> <u>1</u> ① ② ③

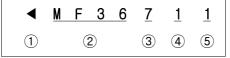
① Year : $7 - 2007 \cdots$

② Month: 1 - January, 2 - February ···· 9 - September, A - October, B - November ··

3 Date : 1 - 1st , 2 - 2nd \cdots A - 10th, B - 11th \cdots

12.4 Marking





- 1 Input Signal
- ② Serial
- ③ Year; 1 2001, 2 2002, ···· 7 2007 ····
- 4 Month; 1 January, 2 February ···· 9 September, A October, B November ····
- ⑤ Date : 1 1st , 2 2nd ···· A 10th, B 11th ····

12.5 Marking type

Ink marking - Using Black Ink

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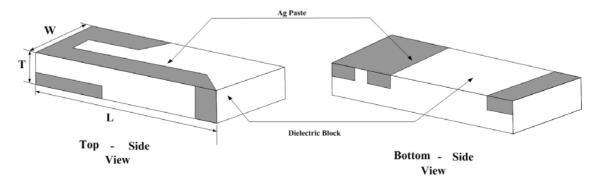


13. Structure and Material

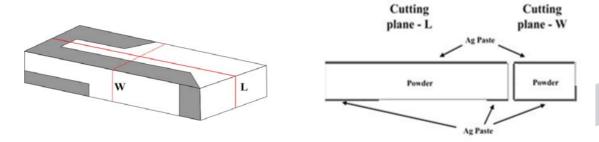
13.1 materialization method

Chip antenna forms the pattern with Ag paste on the brick of dielectric block and materializes the characteristics

13.2 Structure



13.3 Internal cross section



13.4 Material

ITEM	Material	Maker	Printing pattern SPEC
Dielectric Block	Powder	FUJI	
PATTERN	Ag Paste	METECH	Thickness : TYP 10#
PAD	Ag paste	METECH	Thickness: Min 10 µm (TYP 16~20 µm)

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14. Attention

14.1 Temperature Condition

	Range of Temperature	Unit
Application temperature	-40 ∼ +85	°C
Keeping temperature	-40 ∼ +85	°C

14.2 Temperature Test Condition

	Condition	Range of Temperature		
Application temporature	Low	24hr normal action at -75℃		
Application temperature	High	24hr normal action at +150℃		
Vooning tomporature	Low	normal action when left for 1000hr at -75℃		
Keeping temperature	High	normal action when left for 1000hr at +85℃		

* Because of the keeping temperature problem, no admission when left over +85°C



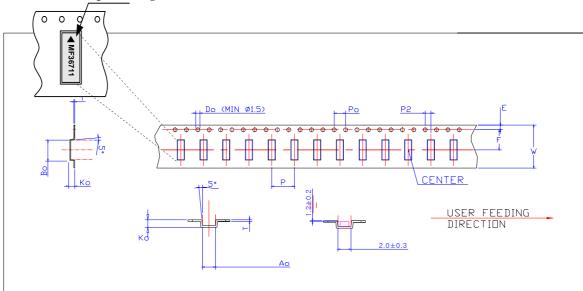
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15. Packing

15.1 Carrier/Reel

ITEM	Material	Surface Resistance	electrostatic emission	Packing method
Carrier tape	A-PET	Typical 10 ⁸ Ω	10V MAX	Hoot proce
Cover tape	PET	Typical 10 ⁸ Ω	30V MAX	Heat press
Reel	PS	Typical 10 ⁸ Ω	30V MAX	-
	Input Marking			



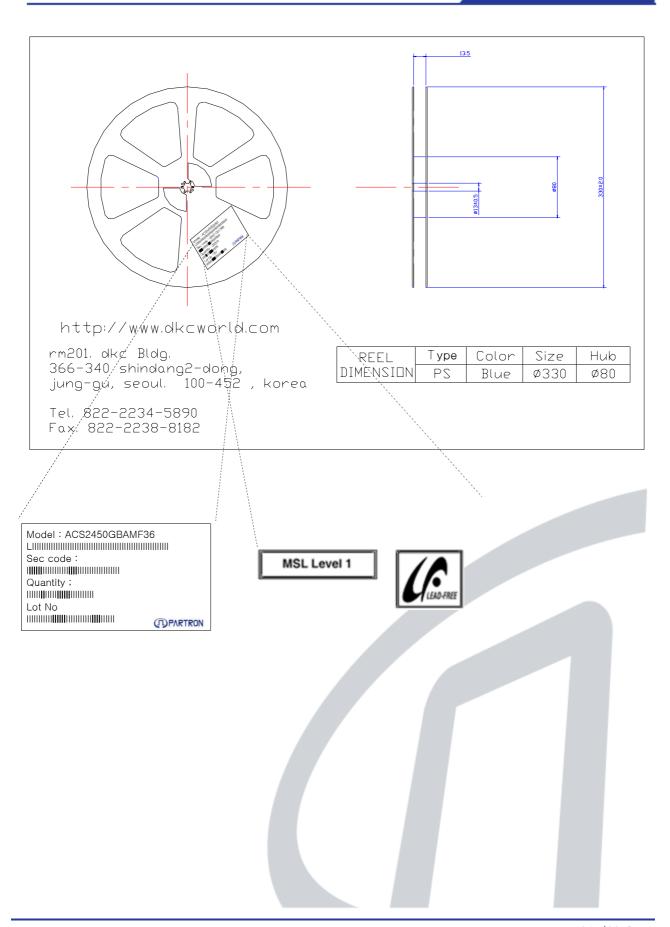
- 1. 10 sprocket hole pitch cumulative tolerance ±0.2
 2. Camber not to exceed 1mm in 100mm.
 3. Ao and Bo measured on a plane 0.1mm above the bottom of the pocket
 4. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.

DKC DWG. No.	J. No. D-1608-028		ARRIER TAPE
DIMENSIONAL UNIT	ММ	2*7*1.2P	
UNTOLERANCED DIMENSION	±0.1	PART.	CARRIER TAPE
		MATERIAL	A-PET
CAD FILE NAME	050617	LENGTH	48.4M
DESIGNED BY	K. M. J		
		COUNT	6050₽
SCALE	1/1		

NAME	SPEC.
W	16.0±0.2
E	1.75±0.1
F	7.5±0.1
Do	1.5+0.1
Р	8.0±0.1
Ро	4.0±0.1
P2	2.0±0.1
Ao	2.3±0.1
Во	7.3±0.1
Ko	1.4±0.1
T	0.3±0.05

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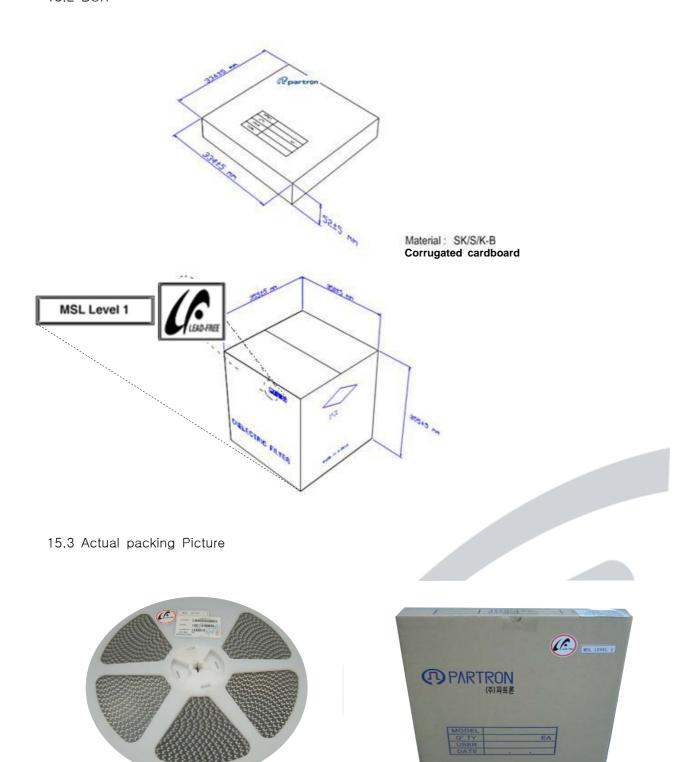




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15.2 BOX



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Internal Box

Ree1



16. Process Control

	Product Issued/Revision			Record	By designed	By chec	ked By	approved						
CHIP ANTENNA		Issued Revised	04.04.0 05.04.0		Process Control			PRCP-C0	01					
Input	FLOW	CHART	Process		Manag	ement of Facto	ors			M	anagement of qua	ity		
Materials	prepar ation	Main Process	name	Equipment Name	Checked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action
Ceramic POWDER		\Diamond	Import Inspection						shrinking rate permittivity	refer to Guide Sheet	Micrometer Network	10ea/L0T	C/sheet	Return
POWDER lubricant			powder	Mixer					mixing	POWDER lubricant	Scale	PER MIXING	-	Exhaust
			Shaping	Press	pressure Mold Condition	refer to Guide Sheet	Per LOT 1/day	parameter C/SHEET	dimension weight density aspect	refer to Guide Sheet	Micrometer scale Calculated Visual	5/100EA 10ea/lot	LOT CARD	Exhaust
			Plasticity	Plasticity Hole	SETTER Outside Temperature PROFILE	refer to Guide Sheet	all 2/day 1/month	C/sheet						
		\Diamond	Block						wide length shape	refer to Guide Sheet	Micrometer Calipers Visual Inspection	20ea/L0T 20ea/L0T all	C/sheet	Exhaust
AG PASTE			SIDE1 PAD Printing	Printer screen	Squeeze velocity/presure SNAP	refer to Guide Sheet	1/day	-	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework
			Dry	Dryer Dry Jig	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot	Rework

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Product CHIP ANTENNA		Is	sued/Revisior	1						Record	By designed	By chec	ked By	approved	
		Issue Revise)1				
Input	FLOW	CHART	Process		Mai	nageme	ent of Factor	S			M	anagement of qual	ity		
Materials	prepar ation	Main Process	name	Equipment Name	Check	ed	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action
AG PASTE			SIDE 2 PAD Printing	Printer screen	Squeez velocity/pr SNAF	resure	refer to Guide Sheet	1/day	-	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework
			Dry	Dryer Dry Jig	Tempera Belt sp		refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework
			Baking	Baking Hole mesh net	Tempera Belt sp	ture beed	refer to Guide Sheet	1/week	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visual Inspection	all	Lot card	Exhaust Rework
AG PASTE			TOP printing	Printer screen	Squeez velocity/pr SNAF	resure	refer to Guide Sheet	1/day	-	PATTERN dimension	refer to Guide Sheet	measure	10ea/3Jig	c/sheet	Rework
			Dry	Dryer Dry Jig	Tempera Belt sp		refer to Guide Sheet	1/week	Parameter	Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework
AG PASTE			BOTTOM PAD Printing CTQ	printer screen	Squeez velocity/pr SNAF	ze resure D	refer to Guide Sheet	1/day	-	PATTERN dimension aspect	refer to Guide Sheet	measure Microscope	10ea/3Jig	c/sheet	Rework

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Product CHIP ANTENNA		Iss	sued/Revisior	1						Record	By designed	By chec	cked [By approved	
		Issued Revised			Process Control					PRCP-C0	01				
Input	FLOW	CHART	Process		М	anagem	ent of Facto	rs			1	Management of qua	ality		
Materials	prepar ation	Main Process	name	Equipment Name	Check	ked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Recor	d Action
			Dry	Dryer Dry Jig	Tempera Belt s		refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot ca	rd Rework
			Baking	Baking Hole mesh net	Tempera Belt s		refer to Guide Sheet	1/week	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visual Inspection	all	Lot ca	rd Exhaust Rework
			aspect inspection							aspect	Reference SPL refer to Guide Sheet	Visual Inspection microscope	all	Lot ca product diary	on .
			MARKING	Marking Machine						marking	Reference SPL	Visual Inspection	all	Lot ca product diary	on
			Electrical Characteristic	NETWORK Inspection Jig	proofre Condi		refer to Guide Sheet	1/2hour	C/sheet	Electrical Characteristic	refer to Guide Sheet	Network	all	Lot ca product diary	on .
			aspect inspection							aspect dimension	Reference SPL refer to Guide Sheet	Visual Inspection microscope	all	Lot ca product diary	on .
Carrier cover reel			Taping							Quantity Direction aspect	refer to Guide Sheet	Manual	all	Lot ca product diary	rd on Rework
			shipper inspection	NETWORK Inspection Jig	proofre Condi		refer to Guide Sheet	1/person	C/sheet	Electrical Characteristic aspect packing	refer to Guide Sheet	Network microscope Visual Inspection	refer to Guide Sheet	Resul Pape	
packing box label			packing	bar code printer						packing P/N Quantity	refer to Guide Sheet	Visual Inspection	all	-	Rework
			packing inspection							packing P/N Quantity	refer to Guide Sheet	Visual Inspection	all	-	return

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17. RoHS Data

1) Ceramic Powder

Parts Name	White Powder(MMS-08)				
Tester Organization	SGS Taiwan LTD.				
Measurement Tester	Please see the 'method' in the test report				
Measurement Data	Please see the report under the table				

SGS

Test Report

FUJI TITANIUM IND. CO., LTD.

12-8, SENOEN-CHO, HIRATSUKA-CITY, KANAKAWAPREF, JAPAN. (T) 81-463-32-0210

Report No. : CE/2006/75167
Date : 2006/07/25
Page : 1 of 4

The following sample(s) was/were submitted and identified by/on behalf of the client as:

Test Result(s) : - Please see the next page(s) -

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Test Report

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INDICAMENDAL HIROGRAPH

: WHITE POWDER

Test Item (s):	Unit	Method	MDI.	Result	
rest reem (s):	Unit	nethod	a MDL		
PBBs (Polybrominated biphenyls)			***		
Monobromobiphenyl	%		0.0005	N.D.	
Dibromobiphenyl	%		0.0005	N.D.	
Tribromobiphenyl	%	7	0.0005	N.D.	
Tetrabromobiphenyl	%	With reference to	0.0005	N.D.	
Pentabromobiphenyl	%	USEPA3540C. Analysis was	0.0005	N.D.	
Hexabromobiphenyl	%	performed by HPLC/DAD,	0.0005	N.D.	
Heptabromobiphenyl	%	LC/MS or GC/MS.	0.0005	N.D.	
Octabromobiphenyl	%	(prohibited by 2002/95/EC	0.0005	N.D.	
Nonabromobiphenyl	%	(ReHS), 83/264/EEC, and	0.0005	N.D.	
Decabromobiphenyi	%	76/769/EECI	0.0005	N.D.	
Total PBBs (Polybrominated biphenyls)/Sum of above	%			N.D.	
PBBEs(PBDEs) (Polybrominated biphenyl ethers)					
Monobromobiphenyl ether	%		0.0005	N.D.	
Dibromobiphenyl ether	%		0.0005	N.D.	
Tribromobiphenyl ether	95] [0.0005	N.D.	
Tetrabromobiphenyl ether	%]	0.0005	N.D.	
Pentabromobiphenyl ether	%	With reference to	0.0005	N.D.	
Hexabromobiphenyl ether	96	USEPA3540C. Analysis was	0.0005	N.D.	
Heptabromobiphenyl ether	%	performed by HPLC/DAD.	0.0005	N.D.	
Octabromobiphenyl ether	96	LC/MS or GC/MS.	0.0005	N.D.	
Nonabromobiphenyl ether % Decabromobiphenyl ether %		(prohibited by 2002/95/EC	0.0005	N.D.	
		(RoHS), 83/264/EEC, and	0.0005	N.D.	
Total PBBEs(PBDEs) (Polybrominated biphenyl ethers)/Sum of above	%	76/769/EEC)	-	N.D.	
Total of Mono to Nona- brominated biphenyl ether. (Note 4)	%			N.D.	

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				Result
Test Item (s):	Unit	Method	MDL	No.1
Chromium VI (Cr+6)	ppm	UV-VIS(US EPA 7196A) after reference to US EPA 3060A.	2	N.D.
Cadmium (Cd)	ppm	ICP-AES after reference to EN 1122, method B:2001 or other acid digestion.	2	N.D.
Mercury (Hg)	ppm	ICP-AES after reference to US EPA 3052 or other acid digestion.	2	N.D.
Lead (Pb)	ppm	ICP-AES after reference to US EPA 3050B or other acid digestion.	2	19.3

NOTE: (1) N.D. - Not Detected (<MDL)
(2) ppm = mg/kg
(3) MDL - Method Detection Limit
(4) Decabromobiphenyl ether (DecaBDE) in polymeric applications is exempted by
Commission Decision of 13 Oct 2005 amending Directive 2002/95/EC notified
under document 2005/717/EC.
(5) PBBEs=PBDEs=Polybrominated Diphenyl Ethers=PBDOs=PBBOs.
(6) "- " = Not Regulation
(7) "---" = Not Applicable

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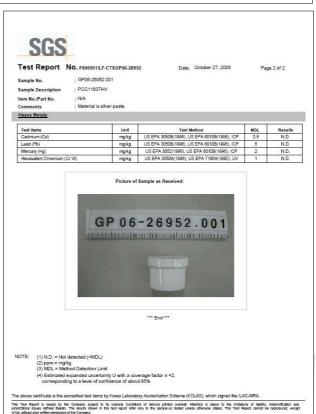




2) Ag Paste

Parts Name	Silver Paste				
Tester Organization	SGS Testing KOREA co. Ltd.				
Measurement Tester	Please see the 'method' in the test report				
Measurement Data	Please see the report under the table				









3) Marking Ink

Parts Name	Black Ink					
Tester Organization	SGS Testing KOREA co. Ltd.					
Measurement Tester	Please see the 'method' in the test report					
Measurement Data	Please see the report under the table					









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